

HVL358CM

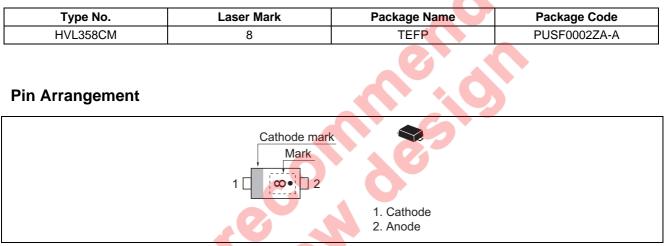
Variable Capacitance Diode for VCO

REJ03G0038-0400 Rev.4.00 Mar 10, 2006

Features

- High capacitance ratio. (n = 2.20 min)
- Low series resistance. (rs = $0.40 \Omega \text{ max}$)
- Good C-V linearity
- Thin Extremely small Flat Lead Package (TEFP) is suitable for surface mount design.

Ordering Information





Absolute Maximum Ratings

(Ta = 25°C)

| Item | Symbol | Value | Unit |
|----------------------|----------------|-------------|------|
| Reverse voltage | V _R | 15 | V |
| Junction temperature | Tj | 125 | °C |
| Storage temperature | Tstg | –55 to +125 | ۵° |

Electrical Characteristics

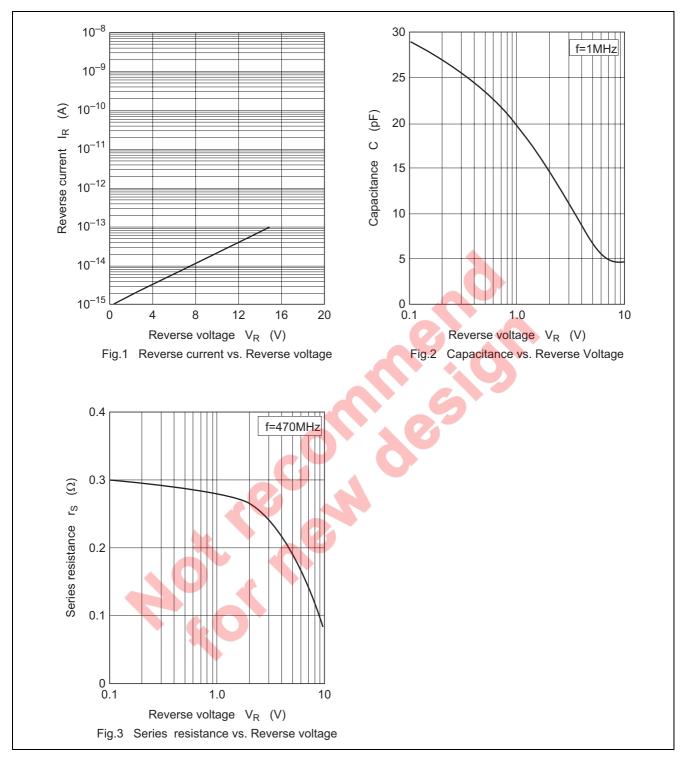
| | | | | | | $(Ta = 25^{\circ}C)$ |
|-------------------|-----------------|-------|-----|-------|------|-----------------------------------|
| Item | Symbol | Min | Тур | Max | Unit | Test Condition |
| Reverse current | I _{R1} | _ | | 10 | nA | V _R = 15 V |
| | I _{R2} | _ | | 100 | | V _R = 15 V, Ta = 60°C |
| Capacitance | C ₁ | 19.50 | | 20.90 | pF | $V_{R} = 1 V, f = 1 MHz$ |
| | C ₄ | 8.30 | | 8.95 | | $V_R = 4 V, f = 1 MHz$ |
| Capacitance ratio | n | 2.20 | | 2.43 | _ (| C ₁ / C ₄ |
| Series resistance | r _S | _ | | 0.40 | Ω | V _R = 1 V, f = 470 MHz |

Note: For TEFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Rev.4.00 Mar 10, 2006 page 2 of 4

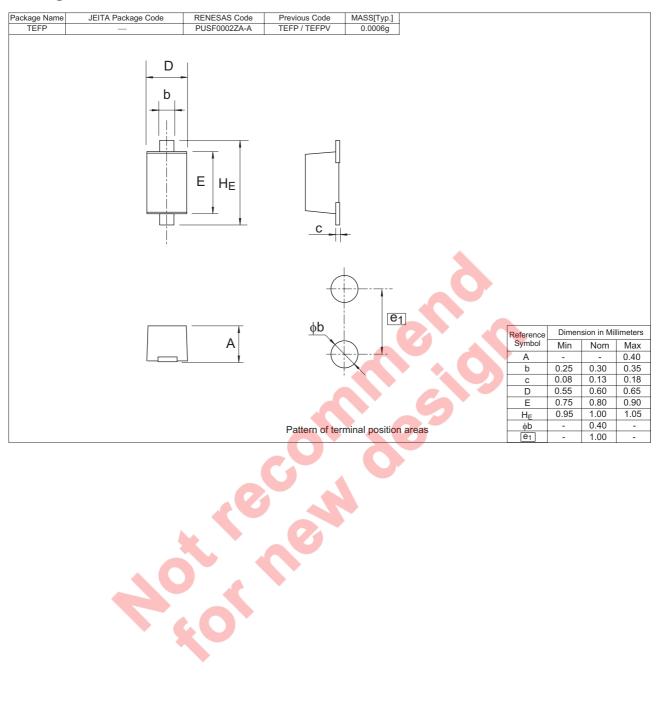


Main Characteristic





Package Dimensions



Rev.4.00 Mar 10, 2006 page 4 of 4



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